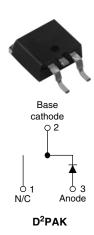


Vishay High Power Products

HEXFRED® Ultrafast Soft Recovery Diode, 8 A



PRODUCT SUMMARY					
V_{R}	1200 V				
V _F at 8 A at 25 °C	3.3 V				
I _{F(AV)}	8 A				
t _{rr} (typical)	28 ns				
T _J (maximum)	150 °C				
Q _{rr} (typical)	140 nC				
dI _{(rec)M} /dt (typical) at 125 °C	85 A/μs				
I _{RRM} (typical)	4.5 A				

FEATURES

- Ultrafast recovery
- · Ultrasoft recovery
- Very low I_{RRM}
- Very low Q_{rr}
- · Specified at operating conditions
- · Designed and qualified for industrial level

BENEFITS

- · Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- · Higher frequency operation
- · Reduced snubbing
- Reduced parts count

DESCRIPTION

HFA08TB120S is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 1200 V and 8 A continuous current, the HFA08TB120S is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to "snap-off" during the tb portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA08TB120S is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Cathode to anode voltage	V_R		1200	V	
Maximum continuous forward current	l _F	T _C = 100 °C	8		
Single pulse forward current	I _{FSM}		130	Α	
Maximum repetitive forward current	I _{FRM}		32		
Maximum power dissipation	P _D	T _C = 25 °C	73.5	W	
Maximum power dissipation	L D	T _C = 100 °C	29	VV	
Operating junction and storage temperature range	T _J , T _{Stg}		- 55 to + 150	°C	

Document Number: 93043 Revision: 22-Oct-08

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply

HFA08TB120S

Vishay High Power Products

HEXFRED® Ultrafast Soft Recovery Diode, 8 A



ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	Ι _R = 100 μΑ	1200	-	-	
		I _F = 8.0 A	-	2.6	3.3	V
Maximum forward voltage V _{FM}	V_{FM}	I _F = 16 A	-	3.4	4.3	
	I _F = 8.0 A, T _J = 125 °C	-	2.4	3.1		
Maximum reverse		$V_R = V_R$ rated	-	0.31	10	
leakage current		$T_J = 125 ^{\circ}\text{C}, V_R = 0.8 ^{\circ}\text{x} ^{\circ}\text{V}_R ^{\circ}\text{rated}$	-	135	1000	μΑ
Junction capacitance	C _T	V _R = 200 V	-	11	20	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nΗ

DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
	t _{rr}	$I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	28	-	
Reverse recovery time	t _{rr1}	T _J = 25 °C		-	63	95	ns
	t _{rr2}	T _J = 125 °C		-	106	160	
Peak recovery current	I _{RRM1}	T _J = 25 °C	I _F = 8.0 A dI _F /dt = 200 A/μs	-	4.5	8.0	Α
	I _{RRM2}	T _J = 125 °C		-	6.2	11	
Reverse recovery charge	1 0 1 7 05 00 1 ' '	$V_{\rm R} = 200 \text{ V}$	-	140	380	nC	
neverse recovery charge	Q _{rr2}	T _J = 125 °C		-	335	880	
Peak rate of fall of recovery current during t _b	dI _{(rec)M} /dt1	T _J = 25 °C		-	133	-	- A/μs
	dI _{(rec)M} /dt2	T _J = 125 °C		-	85	-	Ανμδ

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C
Thermal resistance, junction to case	R _{thJC}		-	-	1.7	K/W
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	40	T IVV
Maight			-	2.0	-	g
Weight			-	0.07	-	OZ.
Marking device		Case style D ² PAK		HFA08	TB120S	

LINKS TO RELATED DOCUMENTS				
Dimensions http://www.vishay.com/doc?95046				
Part marking information	http://www.vishay.com/doc?95054			
Packaging information	http://www.vishay.com/doc?95032			

Document Number: 93043 Revision: 22-Oct-08



Vishay

Disclaimer

All product specifications and data are subject to change without notice.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

Vishay disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications unless otherwise expressly indicated. Customers using or selling Vishay products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Vishay for any damages arising or resulting from such use or sale. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

Product names and markings noted herein may be trademarks of their respective owners.

Document Number: 91000
Revision: 18-Jul-08
www.vishay.com

单击下面可查看定价,库存,交付和生命周期等信息

>>Vishay(威世)